



No. KM 83076

BSI hereby grants to:

**Cemcraft Limited
T/A Cemcraft Electronic
Manufacturing
The Watson Technology Centre
101 New Greenham Park
Newbury
Berkshire
RG19 6HN
United Kingdom**

In respect of:

IPC-A-610D Acceptability of Electronic Assemblies - Class 3

the right and Licence to use the Kitemark in accordance with the Kitemark Licence Conditions of Contract governing the use of the Kitemark, as may be updated from time to time by BSI, and as approved by the Registrar under the Trade Marks Act 1994 (the "Conditions"). All defined terms in this Licence shall have the same meaning as in the Conditions.

The use of the Kitemark is authorized in respect of the Product(s), manufactured at, or provided from, the address above and in conformity with the standard(s) detailed on the following pages.

For and on behalf of BSI:

Alastair Trivett, Managing Director, BSI Product Services – Global

First granted: 1 Jun 2004

Date: 12 Jul 2006

Page: 1 of 4





No. KM 83076

Cemgraft Limited
T/A Cemgraft Electronic
Newbury

Electronic Assembly Types

Single-sided Assembly

Through-hole Component only

Simple Mixed Technology

Complex Mixed Technology

Double-sided Assembly

Surface Mount Components only

Simple Mixed Technology

Complex Mixed Technology

Board Construction Type

Rigid

Flex-Rigid

Detailed Capability

Maximum Board Size Diagonal 60cm

Maximum Through-hole work area 3600 cm²

Maximum Surface Mount work area 2000cm²

Discrete Wiring, Terminals & Connectors Solid Wire
Stranded Wire
Board Connectors

First granted: 1 Jun 2004

Date: 12 Jul 2006

Page: 2 of 4

The licence remains the property of BSI and shall be returned immediately upon request. This licence does not expire. To check its validity telephone: +44 (0)1442 230442

BSI is incorporated by Royal Charter

BSI
Product Services

BSI Product Services

Maylands Avenue, Hemel Hempstead, Hertfordshire HP2 4SQ United Kingdom

Tel: +44 (0)1442 230442 Website: www.bsi-global.com

BSI Group Headquarters: 389 Chiswick High Road, London W4 4AL Tel: +44 (0)208 996 9000



No. KM 83076

Cemgraft Limited
T/A Cemgraft Electronic
Newbury

Through-hole Insertion

Axial; Two Leaded
Radial; Two Leaded
Radial; Multiple Leads
Single In-line Package (SIP)
Dual In-line Package (DIP)
Component Sockets
Card Edge / Two Part Connectors

Surface Mount Placement

Chip Component <0402
Chip Components
Tantalum Capacitors
MELFs
Small Outline Diodes (SODs)
Small Outline Transistors (SOTs)
Small Outline Integrated Circuits (SOICs)
Potentiometers
Sockets, Test Points, Connectors
Quad Flat Pack (QFP)
Thin Small Outline Package (TSOP)
Ball Grid Array ($\leq 1.0\text{mm}$ pitch)
Land Grid Array any pitch

First granted: 1 Jun 2004

Date: 12 Jul 2006

Page: 3 of 4

The licence remains the property of BSI and shall be returned immediately upon request. This licence does not expire. To check its validity telephone: +44 (0)1442 230442

BSI is incorporated by Royal Charter

BSI
Product Services

BSI Product Services

Maylands Avenue, Hemel Hempstead, Hertfordshire HP2 4SQ United Kingdom

Tel: +44 (0)1442 230442 Website: www.bsi-global.com

BSI Group Headquarters: 389 Chiswick High Road, London W4 4AL Tel: +44 (0)208 996 9000



No. KM 83076

Cemgraft Limited
T/A Cemgraft Electronic
Newbury

Attachment Techniques

Manual Soldering
Hot Air Soldering

Cleanliness

No clean system

Coating & Encapsulation

Not claimed

Solder Paste Application

Stencil
Screen

Solder Alloy

Tin-Lead
Lead Free

Inspection

Visual Examination Class 3
Automated Optical
X-ray

This listing details the current process capabilities that have been demonstrated. It should be noted that not all capabilities can be achieved in combination.

First granted: 1 Jun 2004

Date: 12 Jul 2006

Page: 4 of 4